

2U 4-Node BigTwin with 8 hot-swap E3.S 1T NVMe drives per node

Key Applications

All-Flash NVMe Hyperconverged Infrastructure, Container-as-a-Service; Application Accelerator, High-Performance File System, Diskless HPC Clusters,

Key Features

Form Factor

- Four hot-pluggable systems (nodes) in a 2U form factor. Each node supports the following:;
- Dual Socket E2 Intel[®] Xeon[®] 6700/6500 series processors with P-cores or 6700 series processors with E-cores up to 250W with air cooling or 350W with liquid cooling Single CPU configurations supported while maintaining all expansion slot functionality; see Option A for drive support limitations;
- Up to 16 DIMMs supporting up to 4TB DDR5-6400 in 1DPC;
- Flexible networking with OCP 3.0 AIOM slot;
- Up to 2 PCIe 5.0 x16 LP slots Internal PCIe 5.0 for 2x NVMe M.2 support onboard Optional 4x NVMe M.2 support onboard with built-in HW RAID1 via SCC-A2NM2241GH-B1;

2U Rackmount

• Up to 8 front hot-swap E3.S 1T PCIe 5.0 NVMe drive bays;

	Enclosure: 449 x 88 x 730mm (17.68" x 3.47" x 28.75")
	Package: 626 x 248 x 1150mm (24.65" x 9.76" x 45.28")
Processor	Dual Socket E2 (LGA-4710)
	Intel® Xeon® 6700/6500 series processors with P-cores or 6700 series processors with E-cores
	P-cores: Up to 86C/172T; Up to 336MB Cache per CPU
	E-cores: Up to 144C/144T; Up to 108MB Cache per CPU
System Memory	Slot Count: 16 DIMM slots
	Max Memory (1DPC): Up to 4TB 6400MT/s ECC DDR5 RDIMM
Drive Bays Configuration	Default: Total 8 bays
	 8 front hot-swap E3.S 1T PCIe 5.0 NVMe drive bays
	Option A: Total 4 bays • 4 front hot-swap E3.S 1T PCIe 5.0 NVMe drive bays
	M.2: 2 M.2 PCIe 5.0 x4 NVMe slots (M-key 22110(default); VROC required for RAID)
Expansion Slots	Default
	• 2 PCIe 5.0 x16 LP slots
	• 1 PCIe 5.0 x16 AIOM slot (OCP 3.0 compatible)
On-Board Devices	Chipset: System on Chip
	Network Connectivity: Via AIOM
Input / Output	LAN: 1 RJ45 1 GbE Dedicated BMC LAN port
	USB: 2 USB 3.0 Gen2 Type-A ports(Rear)
	Video: 1 VGA port



DATASHEET







	(Front View – System)	(Roar Viow – System)	
Power ButtonLED (Node B (Node A) Node A Node A No	Node D) E B Node C Node D (Noce C) Description 4123 117 Hit-swap RMA Dive Bays (CPU2) 423 117 Hit-swap RMA Dive Bays (CPU2)	Node D Node C Node C Redundert 3500W Tranium Level Power Supplies USB 30 Pots Didicted IPML LAN Port UD Buton Didicted IPML NAN Port Didicted IPML NAN Port UD Buton Didicted IPML NAN Port UD Buton	
System Cooling	Fans: 4x 16K RPM Counter Rotating 80x80x56mm Fan(s) Air Shroud: 4 Air Shrouds Liquid Cooling: Direct to Chip (D2C) Cold Plate (optional)		
Power Supply	2x 3600W Redundant (1 + 1) Titanium Level (96%) power supplies		
System BIOS	BIOS Type: AMI 32MB Flash ROM		
Management	SuperCloud Composer®; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); Supermicro Thin- Agent Service (TAS); SuperServer Automation Assistant (SAA) New!		
PC Health Monitoring	 FAN: Fans with tachometer monitoring Status monitor for speed control Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment CPU: Monitors for CPU Cores, Chipset Voltages, Memory. 8+4 Phase-switching voltage regulator 		
Dimensions and Weight	Weight: Gross Weight: 96.6 lbs (43.8 kg) Net Weight: 66.1 lbs (30 kg) Available Color: Black front & silver body		
Operating Environment	RoHS Compliant Operating Temperature: 10°C to 35°C (50°F to 95°F) Non-operating Temperature: -30°C to 60°C (-22°F to 140°F) Operating Relative Humidity: 8% to 80% (non-condensing) Non-operating Relative Humidity: 8% to 90% (non-condensing)		
Motherboard	Super X14DBT-B		
Chassis	CSE-217BE3Q-R3K60P		